

45V N-Channel SGT MOSFET

General Description		Product Summary				
 Trench Power SGT technology Very low on-resistance R_{DS(ON)} Low Gate Charge Excellent Gate Charge x R_{DS(ON)} Product Applications High Frequency Switching and Synchronous Rectification 			V_{DS} $I_{D} (at V_{GS} = 10V)$ $R_{DS(ON)} (at V_{GS} = 10V)$ $R_{DS(ON)} (at V_{GS} = 4.5V)$ 100% DVDS Tested	45V 100A < 1.7mΩ < 2.4mΩ		
			100% UIS Tested 100% Rg Tested	RoHS		
DF	N5x6	s s G		S D S		
Part Number	Packa	де Туре	Form	Marking		
TSG017N045AT	TSG017N045AT DFN		Tape & Reel	TSG017N045AT		
	•					
Absolute Maximum Ra Parameter	tings (T _A =2	5ºC unless o	therwise noted) Maximum	Units		
	tings (T _A =2	1		Units V		
Parameter	tings (T _A =2	Symbol	Maximum			
Parameter Drain-Source Voltage	tings (T _A =2 T _c =25°C T _c =100°C	Symbol V _{DS}	Maximum 45	V		
Parameter Drain-Source Voltage Gate-Source Voltage	T _C =25⁰C	Symbol V _{DS} V _{GS}	Maximum 45 ±20 100 (package limited)	V V		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current	T _C =25⁰C	Symbol V _{DS} V _{GS} I _D	Maximum 45 ±20 100 (package limited) 100 (package limited)	V V A		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current	T _C =25⁰C	Symbol V _{DS} V _{GS} I _D I _{DM}	Maximum 45 ±20 100 (package limited) 100 (package limited) 400	V V A A		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy	T _c =25°C T _c =100°C	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS}	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58	V V A A A A		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current	T _c =25°C T _c =100°C L =0.3mH ^A	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS}	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58 504.6	V V A A A M M		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS}	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58 504.6 125	V V A A A M M W		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58 504.6 125 50	V V A A A M M W W		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C Junction and Storage Temperatu	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58 504.6 125 50	V V A A A M M W W		
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C Junction and Storage Temperatu Thermal Characteristics	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D T _J , T _{STG}	Maximum 45 ±20 100 (package limited) 100 (package limited) 400 58 504.6 125 50 -55 to 150	V V A A A M A M W W W W V V V		



Electric	al Characteristics(T _J =25°C ur	less otherwise i	noted)	-			-	
Cumk - I	Devemeter	O and division of		Value			Unite	
Symbol	Parameter Conditions			Min	Тур	Max	Units	
STATIC P	ARAMETERS			-	-		-	
BV _{DSS}	Drain-Source Breakdown Voltage	$I_{D} = 250 \mu A, V_{GS} = 0 V$		45			V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =45V, V _{GS} =0V	T _J =25°C			1	- μΑ	
			T _J =125°C			100		
I _{GSS}	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	•			±100	nA	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA		1	1.6	2.4	V	
D	V _{GS} =10V, I _D =30A				1.5	1.7	mΩ	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =30A			2	2.4	mΩ	
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A			56.8		S	
V_{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V				1	V	
I _s	Maximum Body-Diode Continuous Curre	nt ^B			100	А		
DYNAMIC	PARAMETERS				-		-	
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, f =1MH _Z			5096		pF	
C _{oss}	Output Capacitance				1213			
C _{rss}	Reverse Transfer Capacitance				140			
R _g	Gate Resistance	f =1MH _z			3.4		Ω	
SWITCHIN	NG PARAMETERS			-	-		-	
Q _g (10V)	Total Gate Charge	V _{GS} =10V,V _{DS} =20V, I _D =20A			82		nC	
Q _g (4.5V)	Total Gate Charge				38			
Q_{gs}	Gate Source Charge				16			
Q_{gd}	Gate Drain Charge				12			
Q _{oss}	Output Charge	V _{GS} =0V,V _{DS} =20V			49.6			
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 20A,$ $R_{G} = 1.6\Omega$			26		ns	
t _r	Turn-On Rise Time				5			
T _{D(off)}	Turn-Off Delay Time				47			
t _f	Turn-Off Fall Time				10.5			
t _{rr}	Body Diode Reverse Recovery Time	1 =200 di/dt =1000//			35		ns	
Q _{rr}	Body Diode Reverse Recovery Charge	—I _F =20A, di/dt =100A/μs			78		nC	

A. Single pulse width limited by maximum junction temperature.

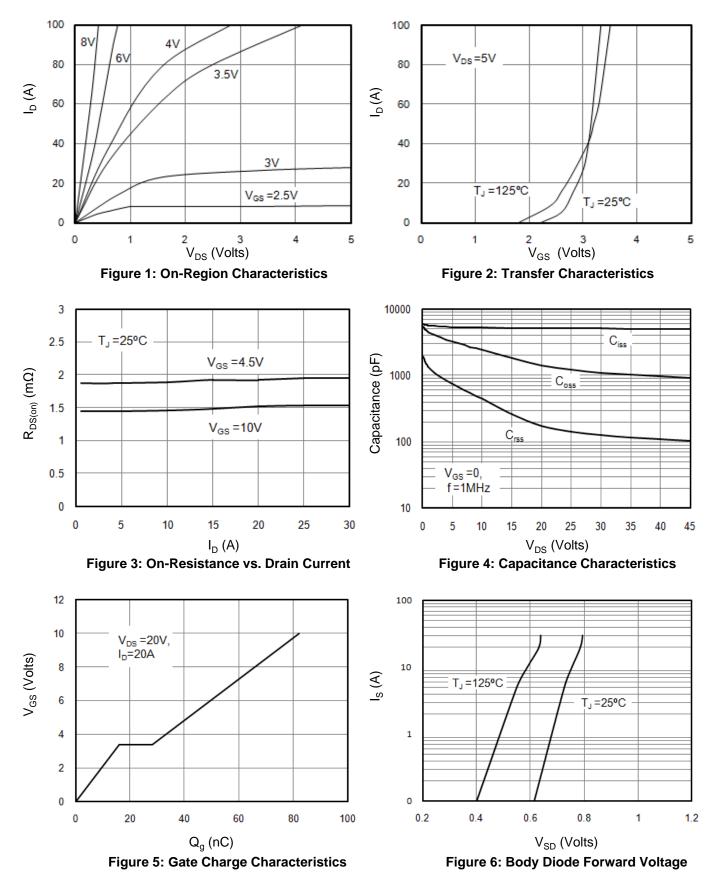
B. The maximum current rating is package limited.

C. The power dissipation P_D is based on $T_{J(MAX)} = 150^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



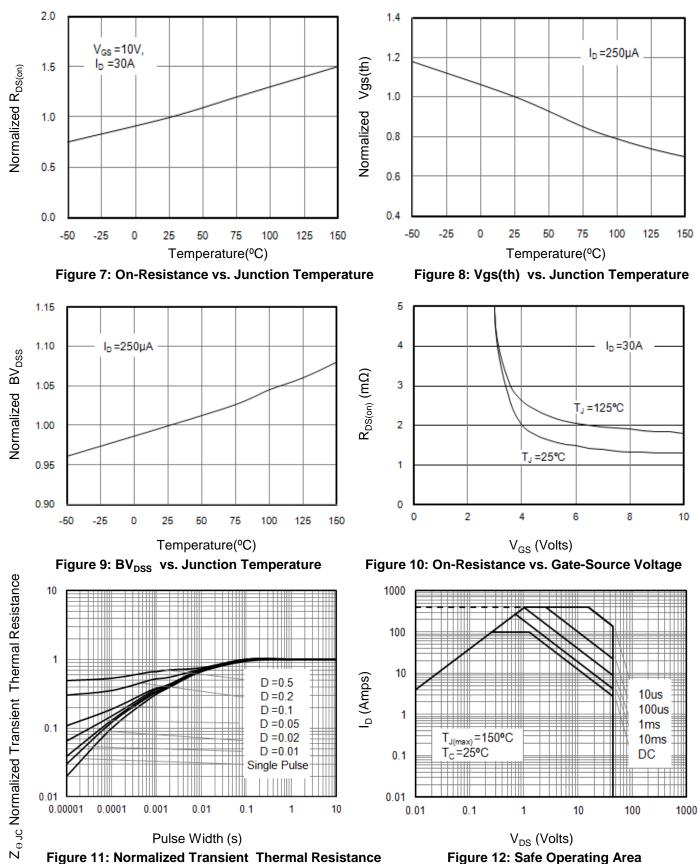


TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



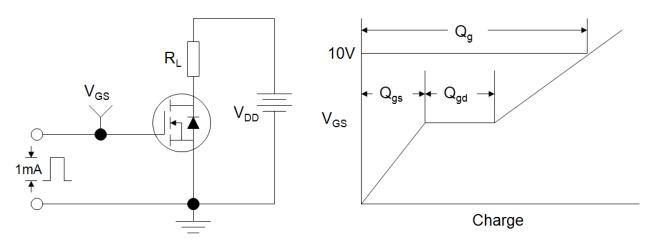


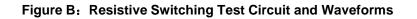
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



V1.0







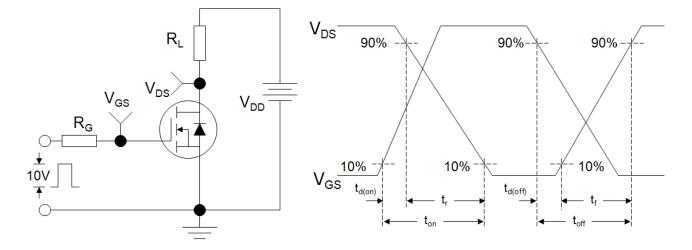
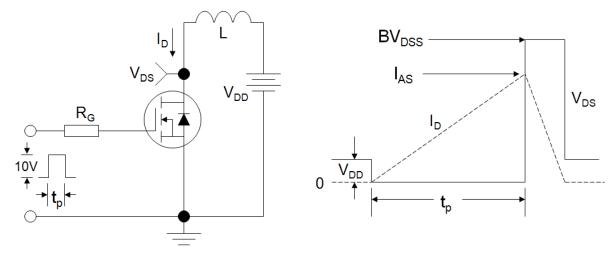
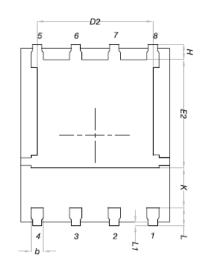
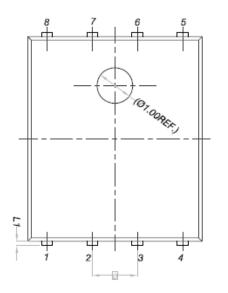
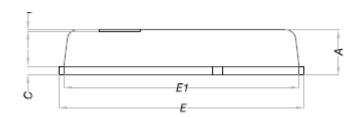


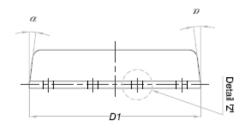
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms











DIM.	MILLIMETERS		0.44	MILLIMETERS			
	MIN.	NOM.	MAX.	DIM.	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10	E	5.90	6.00	6.10
A1	0	-	0.05	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
С	0.20	0.25	0.30	е	1.27 BSC		
D1	4.80	4.90	5.00	Н	0.41	0.51	0.61
D2	3.61	3.81	3.96	К	1.10	-	-
				L	0.51	0.61	0.71
				L1	0.06	0.13	0.20
				α	0°	-	12°

DFN5x6



Disclaimer

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Wuxi Unigroup does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Wuxi Unigroup.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling Wuxi Unigroup products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Wuxi Unigroup for any damages arising or resulting from such use or sale.

Wuxi Unigroup disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Wuxi Unigroup's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Wuxi Unigroup Microelectronics CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Wuxi Unigroup products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only. It is not guaranteed for volume production. Wuxi Unigroup believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by UNIGROUP manufacturer:

Other Similar products are found below :

614233C 648584F MCH3443-TL-E MCH6422-TL-E FDPF9N50NZ FW216A-TL-2W FW231A-TL-E APT5010JVR NTNS3A92PZT5G IRF100S201 JANTX2N5237 2SK2464-TL-E 2SK3818-DL-E FCA20N60_F109 FDZ595PZ STD6600NT4G FSS804-TL-E 2SJ277-DL-E 2SK1691-DL-E 2SK2545(Q,T) D2294UK 405094E 423220D MCH6646-TL-E TPCC8103,L1Q(CM 367-8430-0972-503 VN1206L 424134F 026935X 051075F SBVS138LT1G 614234A 715780A NTNS3166NZT5G 751625C 873612G IRF7380TRHR IPS70R2K0CEAKMA1 RJK60S3DPP-E0#T2 RJK60S5DPK-M0#T0 APT5010JVFR APT12031JFLL APT12040JVR DMN3404LQ-7 NTE6400 JANTX2N6796U JANTX2N6784U JANTXV2N5416U4 SQM110N05-06L-GE3 SIHF35N60E-GE3